

**SCHWEGMAN LUNDBERG WOESSNER & KLUTH**

PATENT, TRADEMARK & COPYRIGHT ATTORNEYS

P.O. Box 2938

Minneapolis, MN 55402

Telephone (612) 373-6900

Facsimile (612) 339-3061

December 16, 2002

TO: Commissioner for Patents  
Attn: Andy Huynh  
Patent Examining Corps  
Facsimile Center  
Washington, D.C. 20231

FROM: Walter W. Nielsen

OUR REF: 884,319US1

TELEPHONE: (602) 298-8920

FAX NUMBER (703) 308-7724

\* Please deliver to Examiner Andy Huynh in Art Unit 2818. \*

Document(s) Transmitted: Amendment and Response Under 37 CFR 1.111; Clean Version of Amended Specification Paragraphs; Clean Version of Pending Claims

Total pages of this transmission, including cover letter: 21

If you do NOT receive all of the pages described above, please telephone us at 612-373-6900, or fax us at 612-339-3061.

In re. Patent Application of: Biswajit Sur et al.

Examiner: Andy Huynh

Serial No.: 09/652,430

Group Art Unit: 2818

Filed: August 31, 2000

Docket No.: 884,319US1

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL INTERFACE

Please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

By: Walter W. Nielsen

Name: Walter W. Nielsen

Reg. No.: Reg. No. 25,539

I hereby certify that this paper is being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below.

Walter W. Nielsen  
Walter W. Nielsen

Dec. 16, 2002  
Date of Transmission

S/N 09/652,430

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: Biswajit Sur et al.

Examiner: Andy Huynh

Serial No.: 09/652,430

Group Art Unit: 2818

Filed: August 31, 2000

Docket: 884.319US1

Title: ELECTRONIC ASSEMBLY COMPRISING SOLDERABLE THERMAL  
INTERFACE

#8/Amend B  
PATENT  
1/11/03

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

Commissioner for Patents  
Washington, D.C. 20231

Applicants have reviewed the Office Action mailed on September 16, 2002. Please amend the above-identified patent application as follows.

**IN THE SPECIFICATION**

Please make the paragraph substitutions indicated in the appendix entitled "Clean Version of Amended Specification Paragraphs". The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs.

The sub-title on page 1, line 8 is amended as follows: Technical Field [of the Invention]

The paragraph beginning on page 1, line 10 is amended as follows:

Embodiments of the [The] present invention relate [relates] generally to electronics packaging. More particularly, the present invention relates to an electronic assembly that includes an integrated circuit package comprising a solderable thermal interface between the integrated circuit and a heat spreader to dissipate heat generated in a high speed integrated circuit, and to manufacturing methods related thereto.

The sub-title on page 1, line 16 is amended as follows: Background Information [of the Invention]